

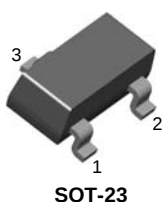


November 2014

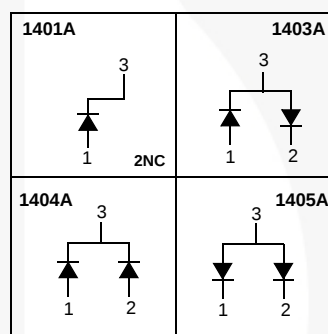
# MMBD1401A / MMBD1403A / MMBD1404A / MMBD1405A High-Voltage General-Purpose Diode

## Descriptions

Sourced from process 2V.



Connection Diagram



## Ordering Information

| Part Number | Top Mark | Package   | Packing Method |
|-------------|----------|-----------|----------------|
| MMBD1401A   | A29      | SOT-23 3L | Tape and Reel  |
| MMBD1403A   | A32      | SOT-23 3L | Tape and Reel  |
| MMBD1404A   | A33      | SOT-23 3L | Tape and Reel  |
| MMBD1405A   | A34      | SOT-23 3L | Tape and Reel  |

MMBD1401A / MMBD1403A / MMBD1404A / MMBD1405A — High-Voltage General-Purpose Diode

## Absolute Maximum Ratings<sup>(1), (2)</sup>

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

| Symbol                | Parameter                                 |                               | Value       | Unit             |
|-----------------------|-------------------------------------------|-------------------------------|-------------|------------------|
| $W_{IV}$              | Working Inverse Voltage                   |                               | 175         | V                |
| $I_O$                 | Average Rectified Current                 |                               | 200         | mA               |
| $I_F$                 | DC Forward Current                        |                               | 600         | mA               |
| $i_f$                 | Recurrent Peak Forward Current            |                               | 700         | mA               |
| $i_{f(\text{surge})}$ | Non-Repetitive Peak Forward Surge Current | Pulse Width = 1.0 second      | 1.0         | A                |
|                       |                                           | Pulse Width = 1.0 microsecond | 2.0         |                  |
| $T_{STG}$             | Storage Temperature Range                 |                               | -55 to +150 | $^\circ\text{C}$ |
| $T_J$                 | Operating Junction Temperature            |                               | 150         | $^\circ\text{C}$ |

### Notes:

- These ratings are based on a maximum junction temperature of  $150^\circ\text{C}$ .
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

## Thermal Characteristics<sup>(3)</sup>

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

| Symbol          | Parameter                               | Max. | Unit                      |
|-----------------|-----------------------------------------|------|---------------------------|
| $P_D$           | Power Dissipation                       | 350  | mW                        |
|                 | Derate above $25^\circ\text{C}$         | 2.8  | mW/ $^\circ\text{C}$      |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 357  | $^\circ\text{C}/\text{W}$ |

### Note:

- Device is mounted on glass epoxy PCB 1.6 inch  $\times$  1.6 inch  $\times$  0.06 inch, mounting pad for the collector lead minimum 0.93 in<sup>2</sup>.

## Electrical Characteristics

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

| Symbol   | Parameter             | Conditions                                                                   | Min. | Max. | Unit |
|----------|-----------------------|------------------------------------------------------------------------------|------|------|------|
| $B_V$    | Breakdown Voltage     | $I_R = 100 \mu\text{A}$                                                      | 250  |      | V    |
| $I_R$    | Reverse Current       | $V_R = 120 \text{ V}$                                                        |      | 40   | nA   |
|          |                       | $V_R = 175 \text{ V}$                                                        |      | 100  | nA   |
| $V_F$    | Forward Voltage       | $I_F = 10 \text{ mA}$                                                        |      | 800  | mV   |
|          |                       | $I_F = 50 \text{ mA}$                                                        | 760  | 920  | mV   |
|          |                       | $I_F = 200 \text{ mA}$                                                       |      | 1.1  | V    |
|          |                       | $I_F = 300 \text{ mA}$                                                       |      | 1.25 | V    |
| $C_O$    | Diode Capacitance     | $V_R = 0, f = 1.0 \text{ MHz}$                                               |      | 2.0  | pF   |
| $T_{RR}$ | Reverse Recovery Time | $I_F = I_R = 30 \text{ mA}$ ,<br>$I_{RR} = 1.0 \text{ mA}, R_L = 100 \Omega$ |      | 50   | nS   |

## Typical Performance Characteristics

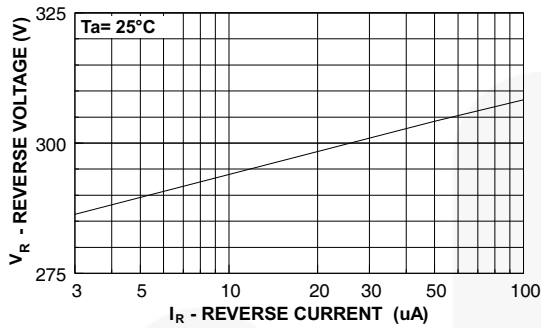


Figure 1. Reverse Voltage vs. Reverse Current  
 $V_R$  - 1.0 to 100  $\mu\text{A}$

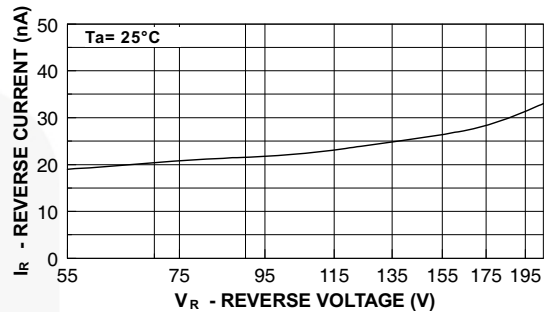


Figure 2. Reverse Current vs. Reverse Voltage  
 $I_R$  - 55 to 205 V

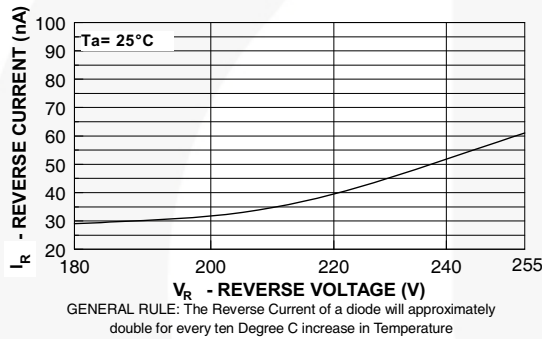


Figure 3. Reverse Current vs. Reverse Voltage  
 $I_R$  - 180 to 255 V

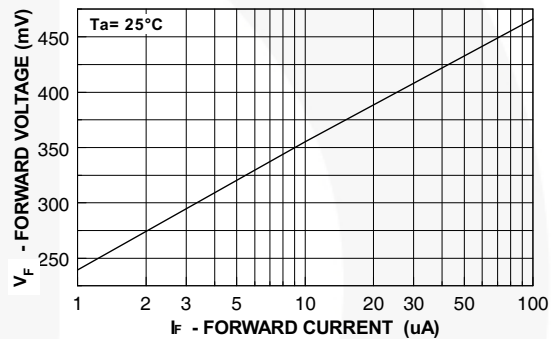


Figure 4. Forward Voltage vs. Forward Current  
 $V_F$  - 1.0 to 100  $\mu\text{A}$

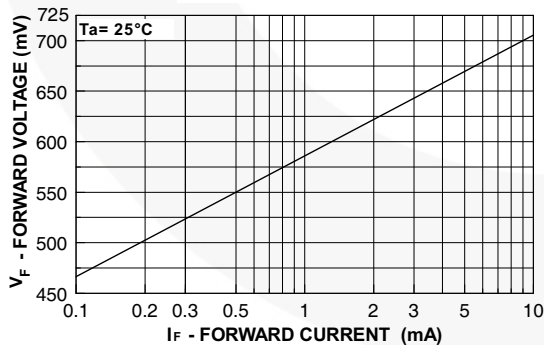


Figure 5. Forward Voltage vs. Forward Current  
 $V_F$  - 0.1 to 10 mA

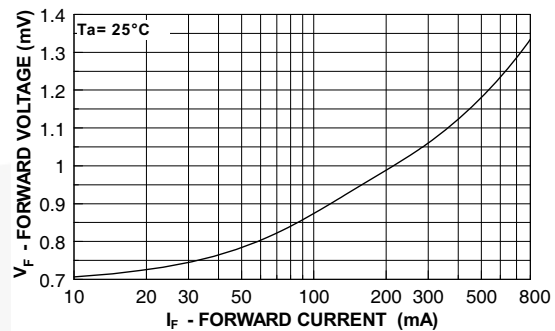


Figure 6. Forward Voltage vs. Forward Current  
 $V_F$  - 10 to 800 mA

## Typical Performance Characteristics (Continued)

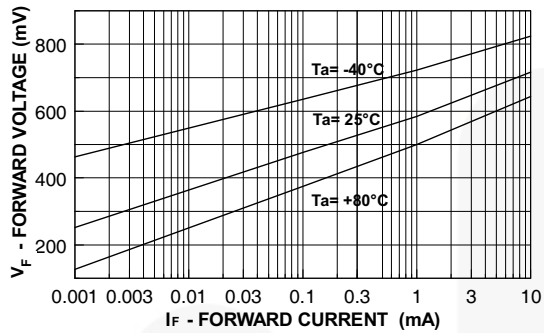


Figure 7. Forward Voltage vs. Ambient Temperature  
 $V_F$  - 1.0  $\mu$ A - 10 mA (- 40 to +80°C)

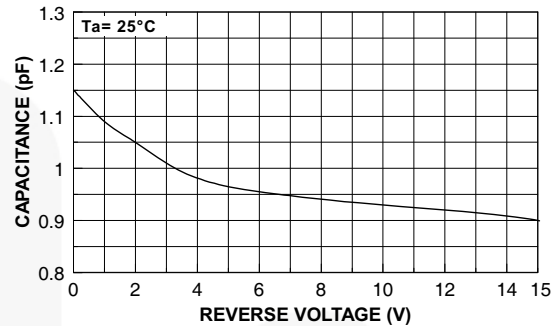


Figure 8. Capacitance vs. Reverse Voltage

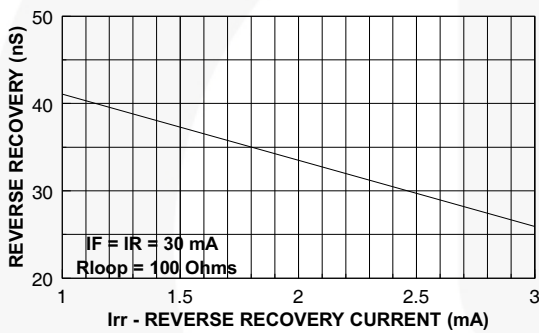


Figure 9. Reverse Recovery Time vs.  
 Reverse Recovery Current ( $I_{RR}$ )

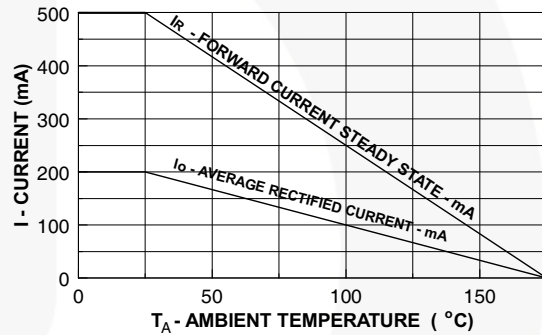


Figure 10. Average Rectified Current ( $I_O$ ) and  
 Forward Current ( $I_F$ ) vs. Ambient Temperature ( $T_A$ )

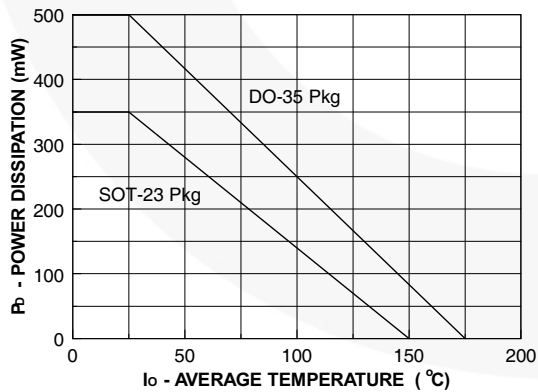
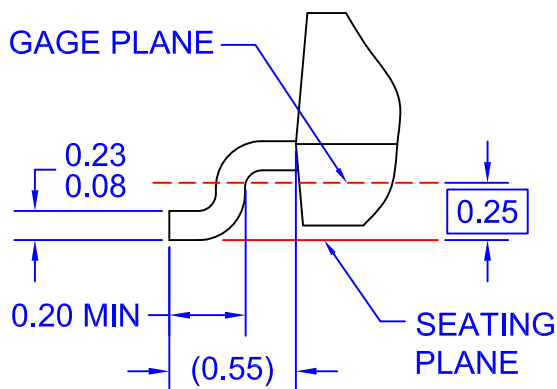
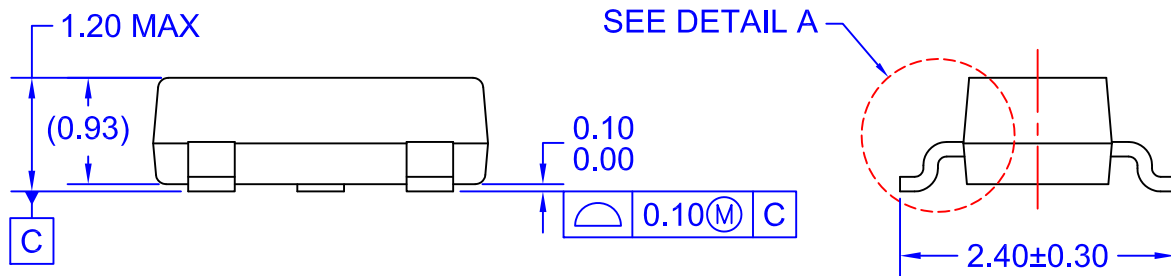
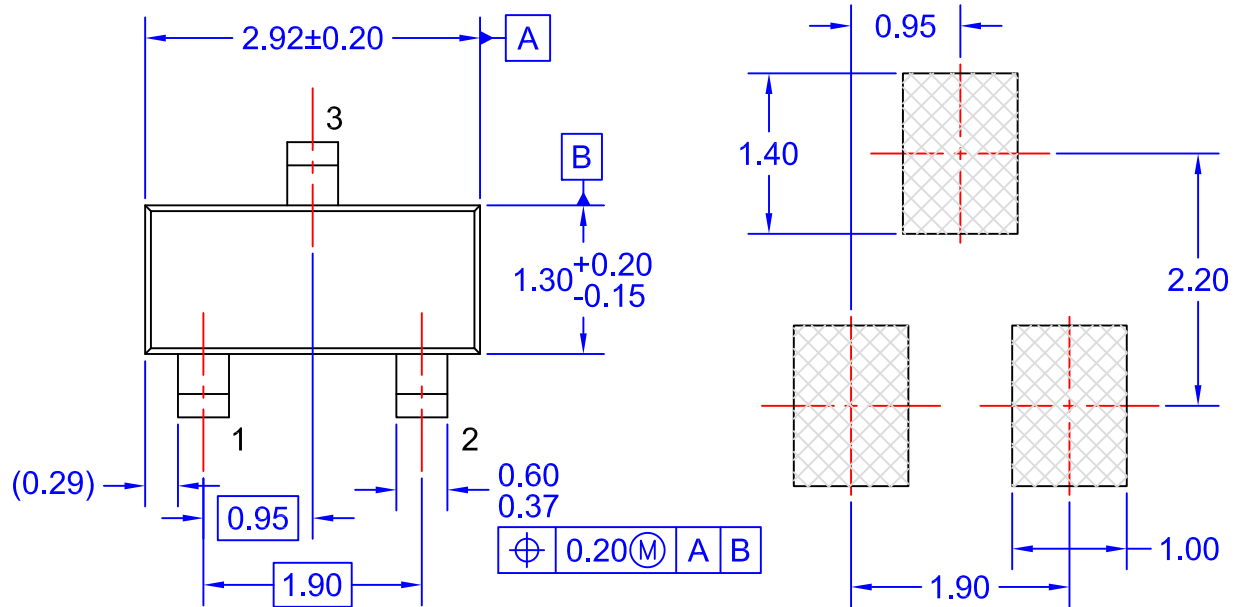


Figure 11. Power Derating Curve



NOTES: UNLESS OTHERWISE SPECIFIED

- A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 2009.
- E) DRAWING FILE NAME: MA03DREV12



ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada

**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910

**Japan Customer Focus Center**  
Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)

**Order Literature:** <http://www.onsemi.com/orderlit>

For additional information, please contact your local  
Sales Representative